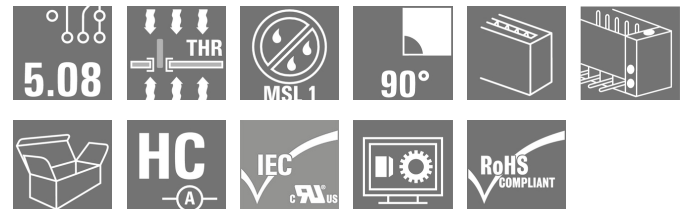


SL-SMT 5.08HC/18/90F 3.2SN BK BX
Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com


High-temperature-resistant pin header, packed in box or tape. On tape, with 1.5 mm solder pin, optimised for automatic assembly. 3.2 mm solder pin suitable for reflow and wave soldering. The pin headers provide space for labelling and can be coded. HC = High Current.

General ordering data

Version	PCB plug-in connector, male header, Flange, THT/THR solder connection, 5.08 mm, Number of poles: 18, 90°, Solder pin length (l): 3.2 mm, tinned, black, Box
Order No.	1837790000
Type	SL-SMT 5.08HC/18/90F 3.2SN BK BX
GTIN (EAN)	4032248347605
Qty.	18 pc(s).
Product data	IEC: 400 V / 27.5 A UL: 300 V / 18.5 A
Packaging	Box

Creation date October 30, 2021 12:16:01 PM CEST

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Technical data

Dimensions and weights

Depth	12 mm	Depth (inches)	0.472 inch
Height	11.7 mm	Height (inches)	0.461 inch
Height of lowest version	8.5 mm	Width	101.6 mm
Width (inches)	4 inch	Net weight	7.83 g

System specifications

Product family	OMNIMATE Signal - series BL/SL 5.08		
Type of connection	Board connection		
Mounting onto the PCB	THT/THR solder connection		
Pitch in mm (P)	5.08 mm		
Pitch in inches (P)	0.2 inch		
Outgoing elbow	90°		
Number of poles	18		
Number of solder pins per pole	1		
Solder pin length (l)	3.2 mm		
Solder pin length tolerance	0 / -0.3 mm		
Solder pin dimensions	d = 1.2 mm, Octagonal		
Solder eyelet hole diameter (D)	1.5 mm		
Solder eyelet hole diameter tolerance (D)	+ 0,1 mm		
L1 in mm	86.36 mm		
L1 in inches	3.4 inch		
Number of rows	1		
Pin series quantity	1		
Protection degree	IP20		
Volume resistance	≤5 mΩ		
Can be coded	Yes		
Plugging force/pole, max.	9 N		
Pulling force/pole, max.	7 N		
Tightening torque	Torque type	Mounting screw, PCB	
	Usage information	Tightening torque	min. 0.15 Nm
			max. 0.2 Nm
		Recommended screw	Part number PTSC KA 2.2X4.5 WN1412

Material data

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	IIIa
Comparative Tracking Index (CTI)	≥ 175	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact material	CuMg
Contact surface	tinned	Layer structure of solder connection	1...3 µm Ni / 2...4 µm Sn matt
Layer structure of plug contact	1...3 µm Ni / 2...4 µm Sn matt	Storage temperature, min.	-40 °C
Storage temperature, max.	70 °C	Operating temperature, min.	-50 °C
Operating temperature, max.	100 °C	Temperature range, installation, min.	-30 °C
Temperature range, installation, max.	100 °C		

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Technical data**Rated data acc. to IEC**

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. number of poles (Tu=20°C)	27.5 A
Rated current, max. number of poles (Tu=20°C)	19 A	Rated current, min. number of poles (Tu=40°C)	24 A
Rated current, max. number of poles (Tu=40°C)	16.5 A	Rated voltage for surge voltage class / pollution degree II/2	400 V
Rated voltage for surge voltage class / pollution degree III/2	320 V	Rated voltage for surge voltage class / pollution degree III/3	250 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	4 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	4 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	4 kV		

Rated data acc. to CSA

Institute (CSA)		Certificate No. (CSA)	200039-1176845
Rated voltage (Use group B / CSA)	300 V	Rated voltage (Use group D / CSA)	300 V
Rated current (Use group B / CSA)	18.5 A	Rated current (Use group D / CSA)	18.5 A
Reference to approval values	Specifications are maximum values, details - see approval certificate.		

Rated data acc. to UL 1059

Institute (UR)		Certificate No. (UR)	E60693
Rated voltage (Use group B / UL 1059)	300 V	Rated voltage (Use group D / UL 1059)	300 V
Rated current (Use group B / UL 1059)	18.5 A	Rated current (Use group D / UL 1059)	10 A
Reference to approval values	Specifications are maximum values, details - see approval certificate.		

Packing

Packaging	Box	VPE length	227 mm
VPE width	339 mm	VPE height	21 mm

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ETIM 8.0	EC002637	ECLASS 9.0	27-44-04-02
ECLASS 9.1	27-44-04-02	ECLASS 10.0	27-44-04-02
ECLASS 11.0	27-46-02-01		

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Technical data

Important note

IPC conformity	Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.
Notes	• Gold-plated contact surfaces on request • Rated current related to rated cross-section & min. No. of poles. • Diameter of solder eyelet D = 1.4+0.1mm • Solder eyelet diameter D = 1.5 + 0.1 mm, from 9 poles • P on drawing = pitch • Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards. • Long term storage of the product with average temperature of 50 °C and average humidity 70%, 36 months

Approvals

Approvals



ROHS	Conform
UL File Number Search	E60693

Downloads

Approval/Certificate/Document of Conformity	Declaration of the Manufacturer
Engineering Data	STEP
Engineering Data	WSCAD
Catalogues	Catalogues in PDF-format
Brochures	FL DRIVES EN MB SMT EN FL DRIVES DE MB DEVICE MANUF. EN FL BUILDING SAFETY EN FL APPL LED LIGHTING EN FL INDUSTR.CONTROLS EN FL MACHINE SAFETY EN FL HEATING ELECTR EN FL APPL INVERTER EN FL BASE STATION EN FL ELEVATOR EN FL POWER SUPPLY EN FL 72H SAMPLE SER EN PO OMNIMATE EN PO OMNIMATE EN

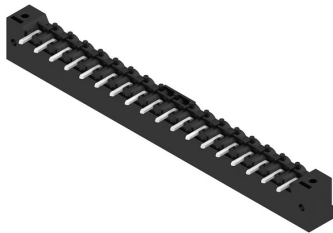
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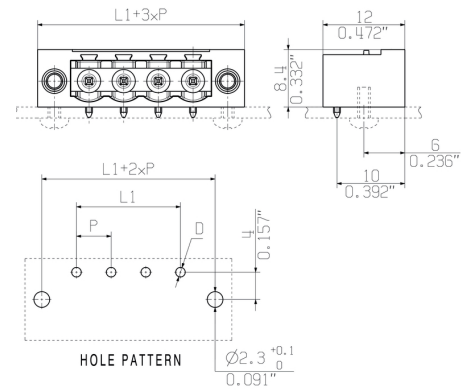
www.weidmueller.com

Drawings

Product image



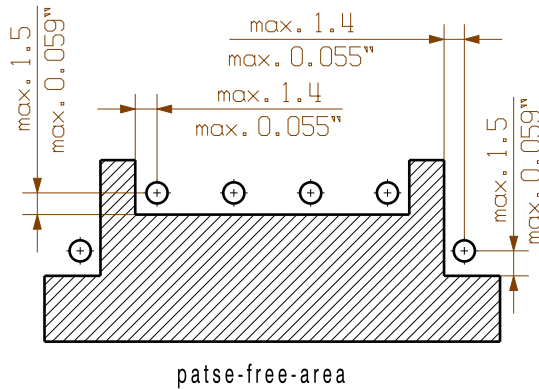
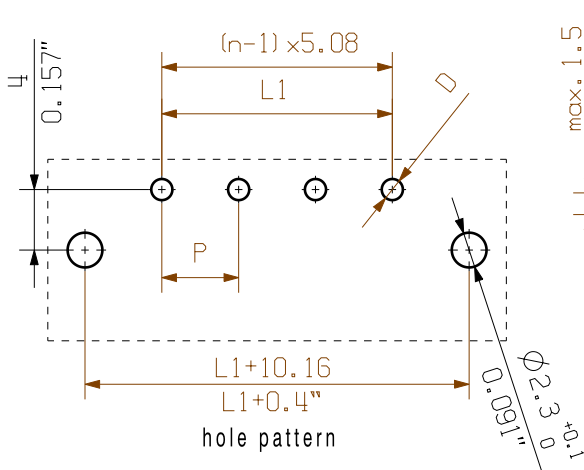
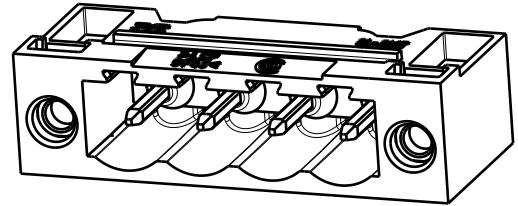
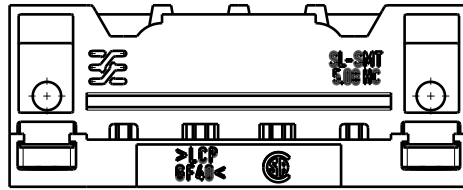
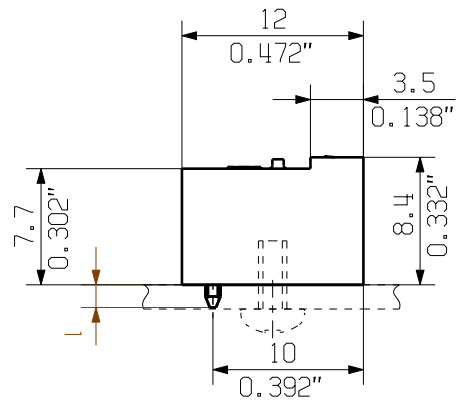
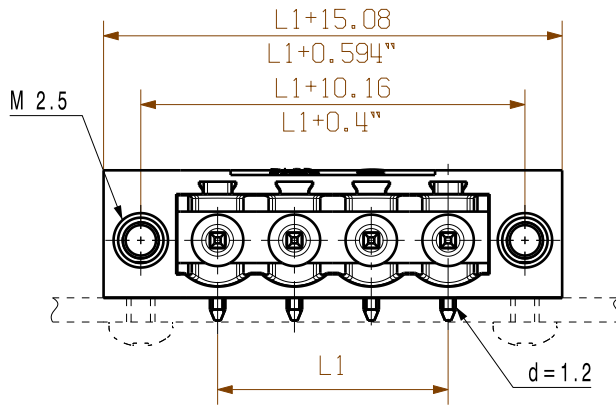
Dimensional drawing



Product benefits



Safe power transmission
Proven properties



D = 1.4/0.055" or 1.5/0.059" (REFLOW SOLDERING)
RECOMMENDATION FOR AUTOMATIC ASSEMBLY
(1.4mm FOR n=2...8 / 1.5mm for n=9...24)

n = POLZAHL/NO OF POLES

P = RASTER/PITCH

For the mounting of PCBs, it should be noted that the rated data relates only to the PCB components alone.

The necessary creepage and clearance paths must be observed in connection with the respective applicant in accordance to IEC 664 / VDE 0110.

The current-carrying capacity and pitch tolerance is to be determined according to DIN IEC 326 part 3 very fine.

Weidmüller PCB components are tested to the DIN EN 61984 standard, and are valid for its field of application.

Provided that the components are used to the intended purpose, all requirements with respect to the occurring of electrical, mechanical, thermic and corrosive stress will be satisfied.

shown: SL-SMT 5.08HC/04/90F

24	116.84	4.600	+/- 0.2
23	111.76	4.400	
22	106.68	4.200	
21	101.60	4.000	
20	96.52	3.800	
19	91.44	3.600	+/- 0.15
18	86.36	3.400	
17	81.28	3.200	
16	76.20	3.000	
15	71.12	2.800	
14	66.04	2.600	+/- 0.1
13	60.96	2.400	
12	55.88	2.200	
11	50.80	2.000	
10	45.72	1.800	
9	40.64	1.600	+/- 0.1
8	35.56	1.400	
7	30.48	1.200	
6	25.40	1.000	
5	20.32	0.800	
4	15.24	0.600	+/- 0.1
3	10.16	0.400	
2	5.08	0.200	
1	tolerance		

4.5	0.1/-0.3
3.2	0.1/-0.3
2.1	0.1/-0.3
1.5	-0.3
1	tolerance

no of poles L1 [mm] L1 [inch] tolerance L1

	DIN ISO 2768-m		106339/4 30.07.18 HERTEL_S 00			Cat.no.: .	
	Modification					2 33262 31	
		Date	Name		SL-SMT 5.08HC/.. /90... STIFTELEISTE MALE HEADER		
Drawn		29.11.2007	HELIS_MA				
Responsible			HERTEL_S				
Checked		01.08.2018	KOCH_JG				
Supersedes: .		Approved	LANG_T		Product file: SL-SMT 5.08		

Recommended wave soldering profiles

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 16
D-32758 Detmold
Germany
Fon: +49 5231 14-0
Fax: +49 5231 14-292083
www.weidmueller.com

Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Recommended reflow soldering profile

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 16
D-32758 Detmold
Germany
Fon: +49 5231 14-0
Fax: +49 5231 14-292083
www.weidmueller.com



Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.